



HM772A

PNP Epitaxial Planar Transistor

Description

The HM772A is designed for use in output stage of amplifier, voltage regulator, DC-DC converter and driver.



SOT-89

Absolute Maximum Ratings

- Maximum Temperatures
 - Storage Temperature -55 ~ +150 °C
 - Junction Temperature +150 °C Maximum
- Maximum Power Dissipation
 - Total Power Dissipation ($T_A=25^{\circ}\text{C}$) 1 W (Note1)
 - Total Power Dissipation ($T_A=25^{\circ}\text{C}$) 2 W (Note2)
 - Total Power Dissipation ($T_A=25^{\circ}\text{C}$) 1.5 W (Note3)
- Maximum Voltages and Currents ($T_A=25^{\circ}\text{C}$)
 - V_{CBO} Collector to Base Voltage -60 V
 - V_{CEO} Collector to Emitter Voltage -50 V
 - V_{EBO} Emitter to Base Voltage -5 V
 - I_C Collector Current (continuous) -3 A
 - I_C Collector Current (pulse) -7 A (Note4)

Note1: When tested in free air condition, without heat sinking.

Note2: When mounted on a 40X40X1mm ceramic board.

Note3: Printed circuit board 2mm thick, collector plating 1cm square or larger.

Note4: Single pulse PW=1ms

Electrical Characteristics ($T_A=25^{\circ}\text{C}$)

Symbol	Min.	Typ.	Max.	Unit	Test Conditions
BV_{CBO}	-60	-	-	V	$I_C=-100\mu\text{A}$
BV_{CEO}	-50	-	-	V	$I_C=-1\text{mA}$
BV_{EBO}	-5	-	-	V	$I_E=-10\mu\text{A}$
I_{CBO}	-	-	-1	μA	$V_{CB}=-30\text{V}$
I_{EBO}	-	-	-1	μA	$V_{EB}=-3\text{V}$
$*V_{CE(sat)}$	-	-0.3	-0.5	V	$I_C=-2\text{A}$, $I_B=-0.2\text{A}$
$*V_{BE(sat)}$	-	-1	-2	V	$I_C=-2\text{A}$, $I_B=-0.2\text{A}$
$*h_{FE1}$	30	-	-		$V_{CE}=-2\text{V}$, $I_C=-20\text{mA}$
$*h_{FE2}$	160	-	320		$V_{CE}=-2\text{V}$, $I_C=-1\text{A}$
f_T	-	80	-	MHz	$V_{CE}=-5\text{V}$, $I_C=-100\text{mA}$, $f=100\text{MHz}$
Cob	-	55	-	pF	$V_{CB}=-10\text{V}$, $f=1\text{MHz}$

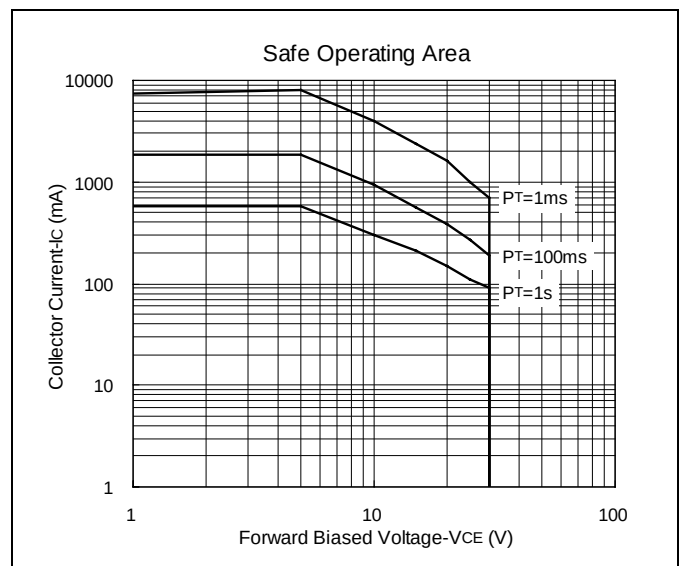
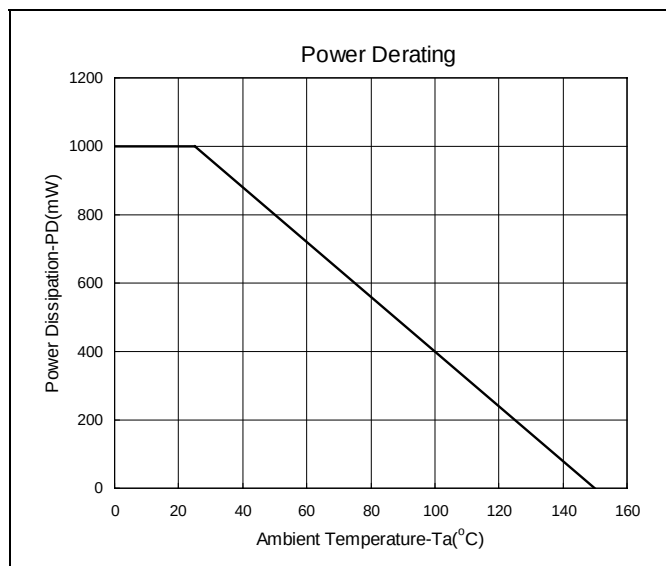
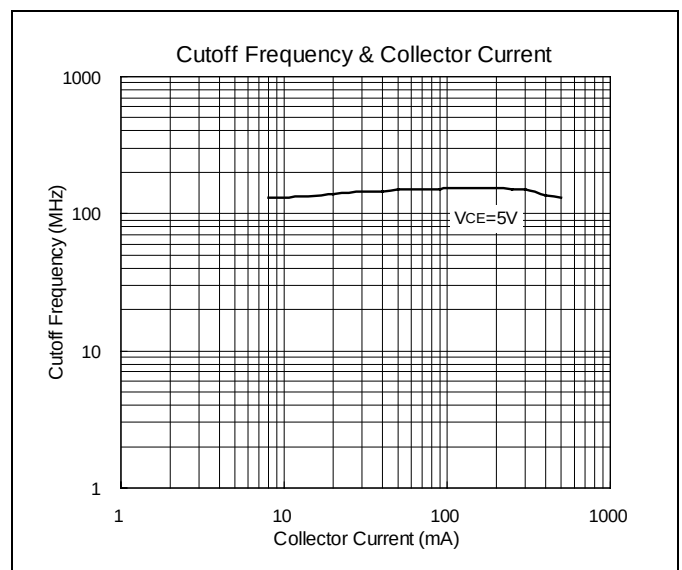
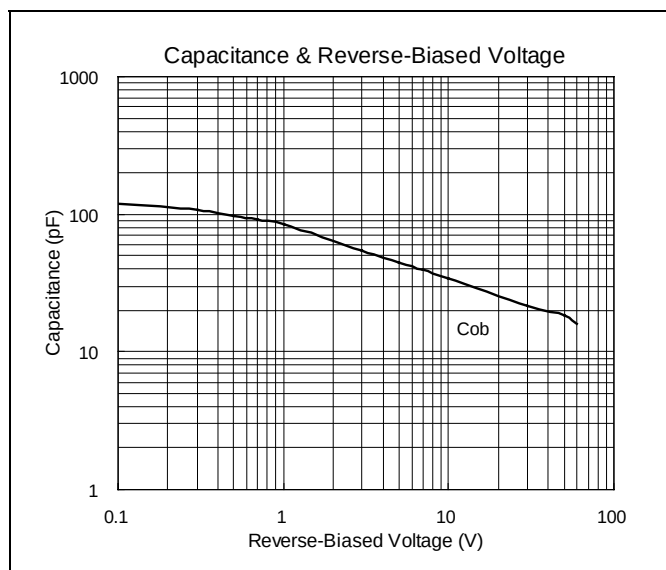
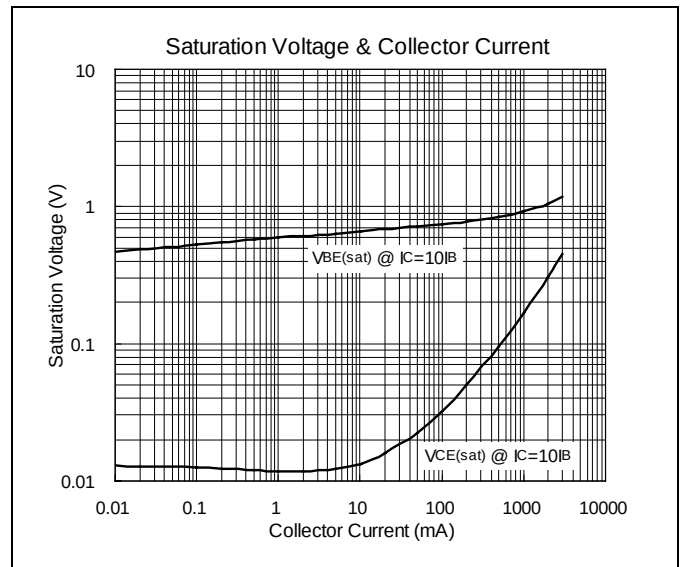
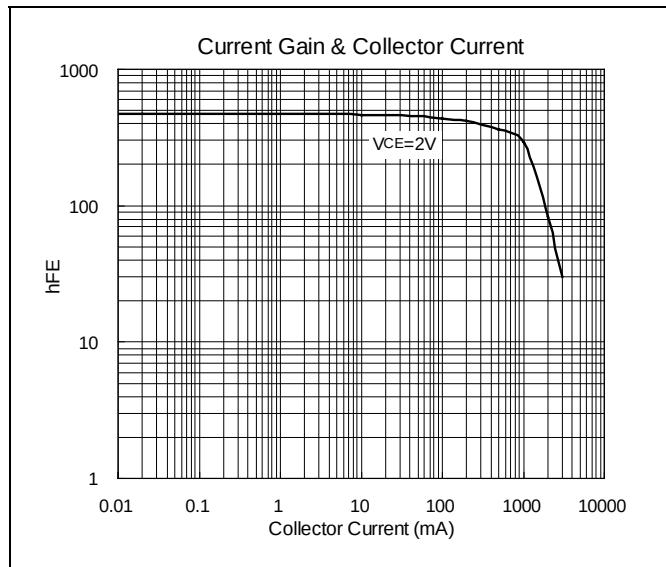
*Pulse Test: Pulse Width $\leq 380\mu\text{s}$, Duty Cycles $\leq 2\%$

Classification Of h_{FE2}

Rank	P
Range	160-320

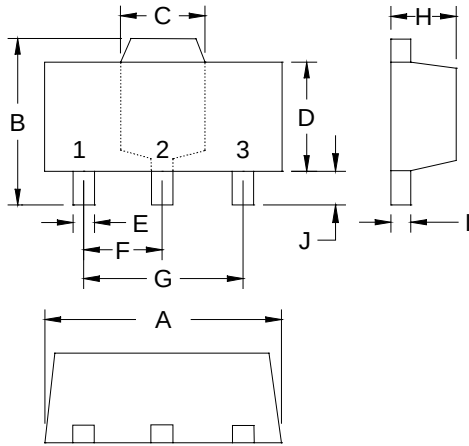


Characteristics Curve



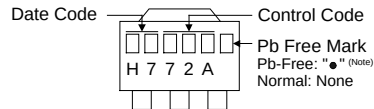


SOT-89 Dimension



3-Lead SOT-89 Plastic
Surface Mounted Package
HSMC Package Code: M

Marking:



Note: Green label is used for pb-free packing

Pin Style: 1.Base 2.Collector 3.Emitter

Material:

- Lead solder plating: Sn60/Pb40 (Normal), Sn/3.0Ag/0.5Cu or Pure-Tin (Pb-free)
- Mold Compound: Epoxy resin family, flammability solid burning class: UL94V-0

DIM	Min.	Max.
A	4.40	4.60
B	4.05	4.25
C	1.50	1.70
D	2.40	2.60
E	0.36	0.51
F	*1.50	-
G	*3.00	-
H	1.40	1.60
I	0.35	0.41

*: Typical, Unit: mm

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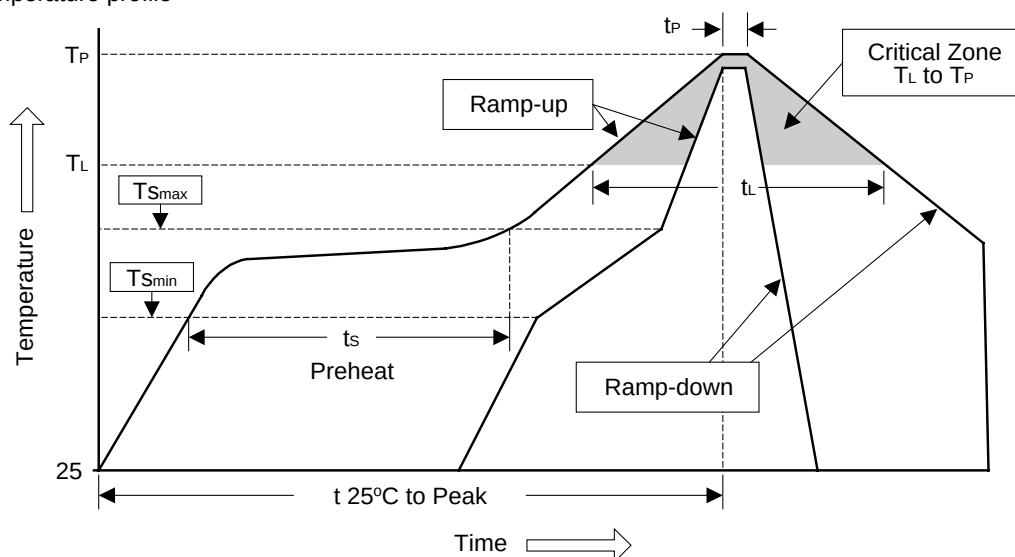
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Soldering Methods for HSMC's Products

1. Storage environment: Temperature=10°C~35°C Humidity=65%±15%
2. Reflow soldering of surface-mount devices

Figure 1: Temperature profile



Profile Feature	Sn-Pb Eutectic Assembly	Pb-Free Assembly
Average ramp-up rate (T_L to T_P)	<3°C/sec	<3°C/sec
Preheat		
- Temperature Min (T_{Smin})	100°C	150°C
- Temperature Max (T_{Smax})	150°C	200°C
- Time (min to max) (t_s)	60~120 sec	60~180 sec
T_{Smax} to T_L		
- Ramp-up Rate	<3°C/sec	<3°C/sec
Time maintained above:		
- Temperature (T_L)	183°C	217°C
- Time (t_L)	60~150 sec	60~150 sec
Peak Temperature (T_P)	240°C +0/-5°C	260°C +0/-5°C
Time within 5°C of actual Peak Temperature (t_p)	10~30 sec	20~40 sec
Ramp-down Rate	<6°C/sec	<6°C/sec
Time 25°C to Peak Temperature	<6 minutes	<8 minutes

3. Flow (wave) soldering (solder dipping)

Products	Peak temperature	Dipping time
Pb devices.	245°C ±5°C	10sec ±1sec
Pb-Free devices.	260°C ±5°C	10sec ±1sec